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**JUNG et al.**(10) **Pub. No.: US 2022/0377875 A1**(43) **Pub. Date: Nov. 24, 2022**(54) **ELECTRONIC DEVICE COMPRISING HEAT  
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**ABSTRACT**

According to various embodiments of the present invention, an electronic device can comprise: a circuit board; an electronic component arranged on one surface of the circuit board; a thermal conductive member arranged so as to correspond to the upper surface of the electronic component; and a thermal interface member arranged between the electronic component and the thermal conductive member and comprising a carbon fiber. The electronic device can be variously implemented according to embodiments.

